2SC4359

Silicon NPN triple diffusion planar type

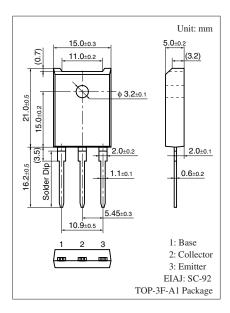
For high breakdown voltage high-speed switching

Features

- High-speed switching
- High collector-base voltage (Emitter open) V_{CBO}
- Wide safe oeration area
- \bullet Satisfactory linearity of forward current transfer ratio h_{FE}

Parameter	Symbol	Rating	Unit	
Collector-base voltage (Emitter open)	V _{CBO}	900	V	
Collector-emitter voltage (E-B short)	V _{CES}	900	V	
Collector-emitter voltage (Base open)	V _{CEO}	800	V	
Emitter-base voltage (Collector open)	V _{EBO}	7	V	
Base current	IB	1	А	
Collector current	I _C	3	А	
Peak collector current	I _{CP}	5	А	
Collector power dissipation	P _C	70	W	
$T_a = 25^{\circ}C$		3.0		
Junction temperature	Tj	150	°C	
Storage temperature	T _{stg}	-55 to +150	°C	

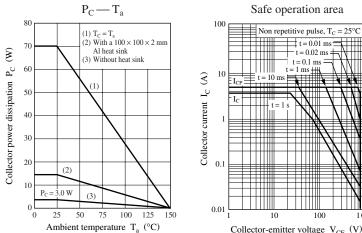




Electrical Characteristics $T_C = 25^{\circ}C \pm 2^{\circ}C$

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Collector-emitter voltage (Base open)	V _{CEO}	$I_{\rm C} = 10 \text{ mA}, I_{\rm B} = 0$	800			V
Collector-base cutoff current (Emitter open)	I _{CBO}	$V_{CB} = 900 \text{ V}, I_E = 0$			50	μΑ
Emitter-base cutoff current (Collector open)	I _{EBO}	$V_{EB} = 7 V, I_C = 0$			50	μΑ
Forward current transfer ratio	h _{FE1}	$V_{CE} = 5 V, I_C = 0.1 A$	8			_
	h _{FE2}	$V_{CE} = 5 \text{ V}, I_C = 0.8 \text{ A}$	6			
Collector-emitter saturation voltage	V _{CE(sat)}	$I_C = 0.8 \text{ A}, I_B = 0.16 \text{ A}$			0.6	V
Base-emitter saturation voltage	V _{BE(sat)}	$I_{C} = 0.8 \text{ A}, I_{B} = 0.16 \text{ A}$			1.2	V
Transition frequency	f _T	$V_{CE} = 5 \text{ V}, I_C = 0.15 \text{ A}, f = 1 \text{ MHz}$		10		MHz
Turn-on time	ton	$I_{C} = 0.8 A$			0.7	μs
Storage time	t _{stg}	$I_{B1} = 0.16 \text{ A}, I_{B2} = -0.32 \text{ A}$			2.5	μs
Fall time	t _f	$V_{CC} = 250 \text{ V}$			0.3	μs

Note) Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.



Safe operation area

t = 0.01 mst = 0.02 mst = 0.1 mst = 1 ms100 1000 Collector-emitter voltage V_{CE} (V)

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